



Part Number : 736560000

Series Number : 73656

Product Category : Backplane Connectors

Product Description : HDM Board-to-Board
Backplane Power Module, Vertical, SMC,
Power Receptacle, 3 Circuits, Gold (Au)
0.76µm

Status : Active

Documents & Resources


- Drawings
- Drawing 736560000_sd.pdf

Packaging Design Drawing PK-70873-0819-001.pdf
- 3D Models and Design Files
- 3D Model 736560000_stp.zip
- Specifications
- Application Specification AS-73656-1998-001.pdf

Product Specification PS-73670-9999-001.pdf

Product Environment Compliance

Compliance

GADSL/IMDS	Not Relevant
China RoHS	
EU ELV	Not Relevant
Low-Halogen Status	Low-Halogen per IEC 61249-2-21
REACH SVHC	Not Contained per D(2023)3788-DC (14 Jun 2023)
EU RoHS	Compliant per EU 2015/863

Multiple Part Product Compliance Statements

- Eu RoHS
- REACH SVHC
- Low-Halogen

Multiple Part Industry Compliance Documents

- IPC 1752A Class C
- IPC 1752A Class D
- Molex Product Compliance Declaration

- IEC-62474
- chemSHERPA (xml)

EU RoHS Certificate of Compliance

Part Details

General

Status	Active
Category	Backplane Connectors
Series	73656
Description	HDM Board-to-Board Backplane Power Module, Vertical, SMC, Power Receptacle, 3 Circuits, Gold (Au) 0.76µm
Application	Backplane
Comments	Backplane Power Module
Component Type	Power Header
Product Family	HDM Backplane Connector System
Product Name	HDM
UPC	800754345361

Agency

CSA	LR19980
UL	E29179

Electrical

Current - Maximum per Contact	15.0A
Data Rate	1.0 Gbps
Voltage - Maximum	500V AC

Physical

Circuits (Loaded)	3
Circuits (maximum)	3
Color - Resin	Black
Durability (mating cycles max)	250
First Mate / Last Break	No
Flammability	94V-0

Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	Beryllium Copper
Material - Plating Mating	Gold
Material - Plating Termination	Gold
Material - Resin	High Temperature Thermoplastic
Net Weight	1.609/g
Number of Columns	1
Number of Pairs	Open Pin Field
Number of Rows	3
Orientation	Vertical
Packaging Type	Tube
PC Tail Length	3.50mm
PCB Locator	No
PCB Retention	Yes
PCB Thickness - Recommended	2.50mm
Pitch - Mating Interface	3.70mm
Pitch - Termination Interface	2.00mm
Plating min - Mating	0.762μm
Plating min - Termination	0.051μm
Polarized to PCB	No
Stackable	Yes
Temperature Range - Operating	-55° to +105°C
Termination Interface Style	Through Hole - Compliant Pin

Solder Process Data

Lead-Free Process Capability	N/A
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